

## ABSTRACT

A resilient, laminated polishing pad for chemical mechanical polishing is disclosed. The polishing pad includes a base layer and a polishing layer bonded by a hot-melt adhesive. The hot-melt adhesive of the present invention provides a T<sub>peel</sub> strength for the polishing pad of at least greater than 40 Newtons at 305 mm/min, reducing pad delamination.